

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC3703EGPBF

(Engineering Calculation)

SSOP

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TOTAL MASS (g): 0.230843

| COMPONENT MATERIAL | VENDOR/INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL Pkg. | | |
|--------------------------------|----------------------------------|--------------------------|--------------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002116 | 1000000 | 13496.2554688 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.122431 | 975000 | 530364.9375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003014 | 24000 | 13056.4960938 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000038 | 300 | 164.614809966 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000088 | 700 | 381.211578369 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead Frame Total: | | | | 0.122871 | 1000000 | 543967.25 |
| | | Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 |
| Exter. Plating Sn | 7440-31-5 | | | 0.003749 | 1000000 | 16240.1835938 | | |
| External Plating Total: | | | | | | 0.003749 | 1000000 | 16240.1835938 |
| Inter. Plating Ni | 7440-02-0 | | | 0.000000 | 0 | 0 | | |
| Inter. Plating Ag | 7440-22-4 | | | 0.001065 | 1000000 | 4353.609375 | | |
| Internal Plating Total: | | | | | | 0.001065 | 1000000 | 4353.609375 |
| Die Attach Total: | | | | | | 0.004814 | 1000000 | 16240.1835938 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000926 | 750000 | 4011.38549005 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000109 | 250000 | 1138.57250977 | | |
| | | Die Attach Total: | | | | 0.001035 | 1000000 | 5349.95800781 |
| | | Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.014342 | 150000 | 62128.8242188 |
| | | | | Bromine (Br) | 40039-93-8 | 0.000956 | 10000 | 4141.34423828 |
| Silica (SiO2) | 60676-86-0 | | | 0.077444 | 810000 | 335483.53125 | | |
| Antimony Trioxide (Sb2O3) | 1309-64-4 | | | 0.002868 | 30000 | 12424.0322266 | | |
| Metal Hydroxide | | | | 0.000000 | 0 | 0 | | |
| Carbon Black (C) | 1333-86-4 | | | 0.000000 | 0 | 0 | | |
| Encapsulation Total: | | | | | | 0.095610 | 1000000 | 414177.71875 |
| Bond Wire Estimated | AFW/TANAKA/Kn | Gold (Au) | 7440-57-5 | 0.000557 | 1000000 | 2412.89599609 | | |

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